

Amendments to the Claims:

1-15. (Cancelled)

16. (Currently Amended) A probe card mountable to a tester for testing a device, wherein the tester includes a test head interphase board, said probe card comprising: a package having solder balls mountable to the test head interphase board, and having a single pad on which is disposed electrically conductive material configured to electrically contact a plurality of bumps on the device.

17. (Previously Presented) The probe card as recited in claim 16, wherein the probe card does not have any probe pins.

18. (Previously Presented) The probe card as recited in claim 16, wherein the probe card is configured to make electrical contact with bumps on the device without using probe pins.

19. (Currently Amended) A method for testing a device under test (DUT), said method comprising: providing a tester which includes a test head interphase board; providing a probe card which includes a package having solder balls mounted to the test head interphase board, and having an a single pad on which is disposed electrically conductive surface material; providing a device under test (DUT)/load board which is configured to retain a substrate, said tester being connected to a Digital Sampling Oscilloscope (DSO); contacting said electrically conductive

Serial No.: 10/692,110
Art Unit: 2829
Page 2

surface material on said single pad of said probe card with a plurality of bumps on the substrate; using said DSO to launch a signal which is received by the substrate, wherein the tester is configured to obtain a waveform from the DSO and store data in a file, wherein said DSO is configured to receive a reflected signal from the substrate and provide the reflected signal to the tester; and using post processing software to analyze the reflected signal and calculate interconnect impedance versus time data for the DUT.

20. (Previously Presented) The method as recited in claim 19, further comprising mounting the probe card to a test head inter phase board of the tester.

21. (Previously Presented) The method as recited in claim 19, further comprising engaging said probe card with the substrate without using any probe pins.

22. (New) A method for measuring package interconnect impedance, said method comprising: providing a tester; providing a tester head; providing a device under test (DUT)/load board which is configured to retain a substrate; providing a Digital Sampling Oscilloscope (DSO) connected to both said tester and said tester head; providing a probe card mounted to said tester head and contactable with said substrate, wherein the probe card comprises a package having solder balls mountable to the test head, and having a single pad on which is disposed electrically conductive material configured to electrically contact a plurality of bumps on the substrate; using said DSO to launch a signal to said tester head which is received by the substrate, wherein said

Serial No.: 10/692,110

Art Unit: 2829

Page 3

DSO is configured to receive the launched signal and a reflected signal from the tester head and provide the signals to the tester; using the tester to obtain a waveform and store data in a file and using post processing software to analyze the data and provide interconnect impedance versus time data, thereby monitoring impedance tolerance.

23. (New) The method as recited in claim 22, wherein said DUT/load board has a socket which is configured to hold said substrate.

24. (New) The method as recited in claim 22, wherein said DUT/load board has signal wires which are connected to the tester, said method further comprising providing a coaxial cable which connects said DSO to said test head, wherein during testing, a signal is launched using the DSO into a coaxial cable which is connected to the test head.

25. (New) The method as recited in claim 22, further comprising providing a GPIB cable which connects said DSO to said tester, wherein the launched signal and the reflected signal are captured back by the DSO, and then fed into the tester via GPIB connections.

Serial No.: 10/692,110

Art Unit: 2829

Page 4